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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

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EXAMINER:

Serial No.: 10/730,333

ART UNIT:

Filing Date: 12/08/2003

FOR: WAFER LEVEL METHODS FOR FABRICATING
MULTI-DICE CHIP SCALE SEMICONDUCTOR
COMPONENTS (AS AMENDED)

Docket No. 02-1500.1

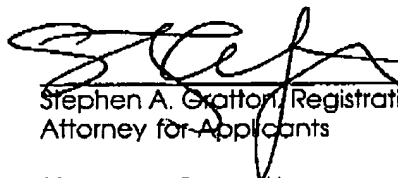
REQUEST FOR FILING RECEIPT
JANUARY 31, 2005

Office of Initial Patent Examination's
Filing Receipt Corrections
Patent & Trademark Office
PO Box 1450
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Dear Sir:

The above application was filed on December 8, 2003. Applicants have not received a Filing Receipt. Attached to this communication is a copy of the return receipt postcard. It is requested that a Filing Receipt be sent to the undersigned.

Respectfully submitted:

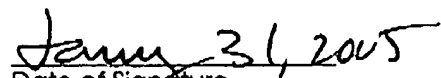


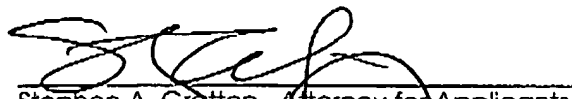
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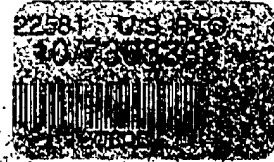
CERTIFICATE OF FACSIMILE TRANSMISSION UNDER 37 C.F.R. 51.8

I hereby certify that this correspondence is being facsimile transmitted to: 703-746-9195 on this 31st day of January, 2005.


Date of Signature


Stephen A. Grotton, Attorney for Applicants

EXPRESS MAIL LABEL NO. ER 499 509 526 US
DATE OF DEPOSIT: DECEMBER 8, 2003



MULTI CHIP SCALE SEMICONDUCTOR COMPONENTS
AND WAFER LEVEL METHODS OF FABRICATION

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Attorney Docket No. 92-1500.1

DIVISION OF SERVICE NO. 10/403,937

The date stamp of the Patent Office hereon may be considered
as the date on which papers indicated below were received:

- Utility Patent Application Transmittal
- Fee Transmittal (in duplicate)
- Declaration and Power of Attorney for Patent Application, pgs 1-4,
from the parent application
- An Election Under 37 CFR §§ 3.71 and 3.73 and Power of Attorney,
from the parent application
- A Preliminary Amendment
- Patent specification comprising pages 1-67, from the parent application
- Twenty-seven sheets of drawings, from the parent application
- An Information Disclosure Statement

Patent Office: Please stamp and return to addressee on reverse side